IEEE 802 Nov 2021 Electronic Plenary

IEEE 802.3 Ethernet WG Opening Plenary 08 Nov 2021

IEEE 802.3
Beyond 400 Gb/s Ethernet SG
Opening Report



IEEE P802.3 B400G Study Group Project information

- Study Group Organization
 - John D'Ambrosia, Study Group Chair
 - Tom Issenhuth, Study Group Recording Secretary
- Task force web and reflector information
 - Reflector information:
 https://www.ieee802.org/3/B400G/reflector.html
 - Home page: https://www.ieee802.org/3/B400G/index.html

Activities Since Jul 2021 Plenary

- Aug 2021 Electronic Session Finalized Project Objectives
 - https://www.ieee802.org/3/B400G/public/21_08/index.html
 - Multiple electronic meetings 8/12, 8/19, 8/26
- Sept 2021 Electronic Session Generated proposed project documentation
 - https://www.ieee802.org/3/B400G/public/21_09/index.html
 - Multiple electronic meetings 9/2, 9/9, 9/28
- Oct 14 Electronic Meeting Reviewed draft Overview presentation.
 - https://www.ieee802.org/3/B400G/public/21_1014/index.html
- Oct 28 Electronic Meeting Overview presentation.
 - https://www.ieee802.org/3/B400G/public/21_1028/index.html

Progress to Date

- Adopted Objectives see backup slides
 - https://www.ieee802.org/3/B400G/proj_doc/objectives_b400g_210826.pdf
- Adopted PAR / CSD
 - PAR: https://mentor.ieee.org/802-ec/dcn/21/ec-21-0224-01-00EC-par-ieee-p802-3df.pdf
 - CSD: https://mentor.ieee.org/802-ec/dcn/21/ec-21-0225-00-00EC-csd-ieee-p802-3df.pdf
- Gave overview presentation of IEEE P802.3df Project to 802.3 WG.

802.3 Nov Plenary Plans

- Nov 2021 Plenary Meeting (11/16, 10am to 12 noon, ET)
- Goals -
 - Request SG Rechartering
 - Consider comments submitted against Project Documentation
 - Consider liaison responses
 - to OIF https://www.ieee802.org/3/minutes/sep21/incoming/OIF_liaison_letter_IEEE802.3_800G_10S
 ept21_Redacted.pdf
 - to ITU-T SG15 https://www.ieee802.org/3/minutes/sep21/incoming/SG15-LS324_Redacted.pdf
 - **GET IEEE P802.3df Project Documentation Approved!**

THANK YOU!



BACKUP OBJECTIVES

Objectives IEEE 802.3 Beyond 400 Gb/s Ethernet Study Group

John D'Ambrosia, Chair, IEEE 802.3 Beyond 400 Gb/s Ethernet Study Group Futurewei, U.S. Subsidiary of Huawei

August 26, 2021

B400G Adopted Objectives

Non-Rate Specific

- Support full-duplex operation only *
- Preserve the Ethernet frame format utilizing the Ethernet MAC *
- Preserve minimum and maximum FrameSize of current IEEE 802.3 standard *
- Support a BER of better than or equal to 10 -13 at the MAC/PLS service interface (or the frame loss ratio equivalent) **
- Provide support to enable mapping over OTN ***

200 Gb/s Related

- Support a MAC data rate of 200 Gb/s ##
- Support optional single-lane 200 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications **
- Define a physical layer specification that supports 200 Gb/s operation:
 - over 1 pair of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter ^
 - over 1 pair of SMF with lengths up to at least 500 m ##
 - over 1 pair of SMF with lengths up to at least 2 km ##

400 Gb/s Related

- Support a MAC data rate of 400 Gb/s ##
- Support optional two-lane 400 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip
 applications ##
- Define a physical layer specification that supports 400 Gb/s operation:
 - over 2 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter ^
 - over 2 pairs of SMF with lengths up to at least 500 m ##

B400G Adopted Objectives

800 Gb/s Related

- Support a MAC data rate of 800 Gb/s *
- Support optional eight-lane 800 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip
 applications ****
- Support optional four-lane 800 Gb/s attachment unit interfaces for chip-to-module and chip-to-chip applications ****
- Define a physical layer specification that supports 800 Gb/s operation:
 - over 4 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter ^
 - over eight lanes of twin axial copper cables with a reach up to at least 2 meters @
 - over eight lanes over electrical backplanes supporting an insertion loss ≤ 28dB at 26.56GHz @
 - over 8 pairs of MMF with lengths up to at least 50 m *
 - over 8 pairs of MMF with lengths up to at least 100 m *
 - over 8 pairs of SMF with lengths up to at least 500 m *
 - over 8 pairs of SMF with lengths up to at least 2 km #
 - over 4 pairs of SMF with lengths up to at least 500 m *
 - over 4 pairs of SMF with lengths up to at least 2 km *
 - over 4 wavelengths over a single SMF in each direction with lengths up to at least 2 km *
 - over a single SMF in each direction with lengths up to at least 10 km *
 - over a single SMF in each direction with lengths up to at least 40 km *

B400G Adopted Objectives

1.6 Tb/s Related

- Support a MAC data rate of 1.6 Tb/s #
- Support optional sixteen-lane 1.6 Tb/s attachment unit interfaces for chip-to-module and chip-to-chip
 applications ***
- Support optional eight-lane 1.6 Tb/s attachment unit interfaces for chip-to-module and chip-to-chip applications #
- Define a physical layer specification that supports 1.6 Tb/s operation:
 - over 8 pairs of copper twin-axial cables in each direction with a reach of up to at least 1.0 meter ^
 - over 8 pairs of SMF with lengths up to at least 500 m #
 - over 8 pairs of SMF with lengths up to at least 2 km #

Adoption History

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*
     Adopted by B400G SG, Apr 2021
**
     Adopted by B400G SG Apr 26, 2021
***
     Adopted by B400G SG May 3, 2021
***
     Adopted by B400G SG May 17, 2021
#
     Adopted by B400G SG Jun 3, 2021
##
     Adopted by B400G SG Jul 13, 2021
###
     Adopted by B400G SG Jul 20, 2021
     Adopted by B400G SG Aug 12, 2021
@
     Adopted by B400G SG Aug 26, 2021
```